

# STP10LN80K5

## N-channel 800 V, 0.55 Ω typ., 8 A MDmesh™ K5 Power MOSFET in a TO-220 package

Datasheet - production data

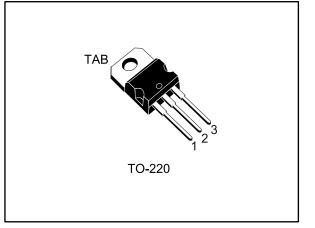
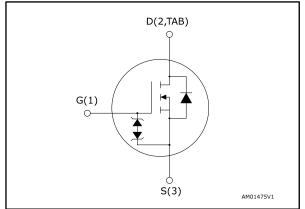


Figure 1: Internal schematic diagram



### **Features**

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max.	ID
STP10LN80K5	800 V	0.63 Ω	8 A

- Industry's lowest R<sub>DS(on)</sub> x area
- Industry's best figure of merit (FoM)
- Ultra-low gate charge
- 100% avalanche tested
- Zener-protected

### **Applications**

• Switching applications

### Description

This very high voltage N-channel Power MOSFET is designed using MDmesh<sup>™</sup> K5 technology based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance and ultra-low gate charge for applications requiring superior power density and high efficiency.

#### Table 1: Device summary

Order code	Marking	Package	Packing
STP10LN80K5	10LN80K5	TO-220	Tube

This is information on a product in full production.

### Contents

## Contents

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## 1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V <sub>GS</sub>	Gate-source voltage	± 30	V
Ι <sub>D</sub>	Drain current (continuous) at $T_c = 25 \ ^{\circ}C$	8	А
ID	Drain current (continuous) at T <sub>c</sub> = 100 °C	5	А
I <sub>DM</sub> <sup>(1)</sup>	Drain current (pulsed)	32	А
P <sub>TOT</sub>	Total dissipation at $T_C = 25 \text{ °C}$	110	W
dv/dt <sup>(2)</sup>	Peak diode recovery voltage slope	4.5	
dv/dt <sup>(3)</sup>	MOSFET dv/dt ruggedness	50	V/ns
Tj	Operating junction temperature	55 to 150	°C
T <sub>stg</sub>	Storage temperature	- 55 to 150	C

#### Notes:

 $^{(1)}\mbox{Pulse}$  width limited by safe operating area

 $^{(2)}I_{SD}$   $\leq$  8 A, di/dt 100 A/µs; V\_Ds peak < V(BR)DSS, V\_DD= 640 V

 $^{(3)}V_{DS} \le 640 \text{ V}$ 

#### Table 3: Thermal data

Symbol	Parameter	Value	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case	1.14	°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-ambient	62.5	°C/W

#### Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I <sub>AR</sub>	Avalanche current, repetitive or not repetitive (pulse width limited by $T_{jmax})$	2.7	А
E <sub>AS</sub>	Single pulse avalanche energy (starting $T_j$ = 25 °C, $I_D$ = $I_{AR},$ $V_{DD}$ = 50 V)	240	mJ



#### 2 **Electrical characteristics**

 $T_C = 25$  °C unless otherwise specified

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS}$ = 0 V, $I_D$ = 1 mA	800			V
		$V_{GS} = 0 V, V_{DS} = 800 V$			1	μΑ
I <sub>DSS</sub>	Zero gate voltage drain current	$V_{GS} = 0 V, V_{DS} = 800 V$ $T_{C} = 125 \text{ °C}$			50	μA
I <sub>GSS</sub>	Gate body leakage current	$V_{DS}$ = 0 V, $V_{GS}$ = ±20 V			±10	μΑ
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DD} = V_{GS}, I_D = 100 \ \mu A$	3	4	5	V
R <sub>DS(on)</sub>	Static drain-source on-resistance	$V_{GS}$ = 10 V, I <sub>D</sub> = 4 A		0.55	0.63	Ω

### Table 5: On/off-state

#### Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C <sub>iss</sub>	Input capacitance		-	427	-	pF
C <sub>oss</sub>	Output capacitance	V <sub>DS</sub> = 100 V, f = 1 MHz, V <sub>GS</sub> = 0 V	-	43	-	pF
C <sub>rss</sub>	Reverse transfer capacitance	163 - 0 1	-	0.25	-	pF
$C_{o(tr)}^{(1)}$	Equivalent capacitance time related	V <sub>DS</sub> = 0 to 640 V,	-	72	-	pF
C <sub>o(er)</sub> <sup>(2)</sup>	Equivalent capacitance energy related	$V_{GS} = 0 V$		27	-	pF
Rg	Intrinsic gate resistance	$f = 1 \text{ MHz}$ , $I_D = 0 \text{ A}$	-	7	-	Ω
Qg	Total gate charge	$V_{DD} = 640 \text{ V}, \text{ I}_{D} = 8 \text{ A}$	-	15	-	nC
Q <sub>gs</sub>	Gate-source charge	V <sub>GS</sub> = 10 V	-	4.2	-	nC
Q <sub>gd</sub>	Gate-drain charge	See Figure 16: "Test circuit for gate charge behavior"	-	9	-	nC

#### Notes:

 $^{(1)}\mbox{Time}$  related is defined as a constant equivalent capacitance giving the same charging time as Coss when  $V_{DS}$ increases from 0 to 80%  $V_{\text{DSS}}$ 

<sup>(2)</sup>Energy related is defined as a constant equivalent capacitance giving the same stored energy as Coss when V<sub>DS</sub> increases from 0 to 80% V<sub>DSS</sub>

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit	
t <sub>d(on)</sub>	Turn-on delay time	$V_{DD}\text{=}$ 400 V, $I_D$ = 4 A, $R_G$ = 4.7 $\Omega$	-	11.8	-	ns	
tr	Rise time	V <sub>GS</sub> = 10 V	-	10	-	ns	
t <sub>d(off)</sub>	Turn-off delay time	See Figure 15: "Test circuit for resistive load switching times"	-	28	-	ns	
t <sub>f</sub>	Fall time	and Figure 20: "Switching time waveform"	-	13	-	ns	

Table 7: Switching times





#### Electrical characteristics

Table 8: Source-drain diode							
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit	
I <sub>SD</sub>	Source-drain current		-		8	А	
I <sub>SDM</sub> <sup>(1)</sup>	Source-drain current (pulsed)		-		32	А	
V <sub>SD</sub> <sup>(2)</sup>	Forward on voltage	$I_{SD} = 8 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.5	V	
t <sub>rr</sub>	Reverse recovery time	I <sub>SD</sub> = 8 A, di/dt = 100 A/µs,V <sub>DD</sub> =		350		ns	
Q <sub>rr</sub>	Reverse recovery charge	60 V See Figure 17: "Test circuit for	-	3.9		μC	
I <sub>RRM</sub>	Reverse recovery current	inductive load switching and diode recovery times"	-	22.5		А	
t <sub>rr</sub>	Reverse recovery time	I <sub>SD</sub> = 8 A, di/dt = 100 A/µs V <sub>DD</sub> =	-	505		ns	
Qrr	Reverse recovery charge	$60 \text{ V}, \text{ T}_{i} = 150 \text{ °C}$ See Figure 17: "Test circuit for	-	5		μC	
I <sub>RRM</sub>	Reverse recovery current	inductive load switching and diode recovery times"	-	20		А	

#### Notes:

<sup>(1)</sup>Pulse width limited by safe operating area

 $^{(2)}\text{Pulsed:}$  pulse duration = 300  $\mu\text{s},$  duty cycle 1.5%

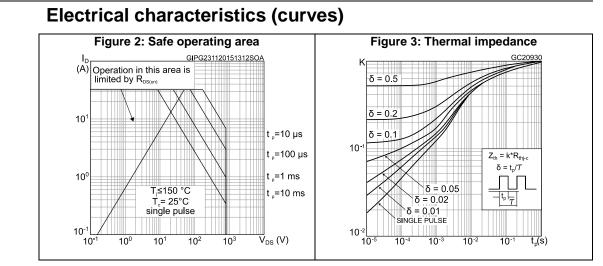
#### Table 9: Gate-source Zener diode

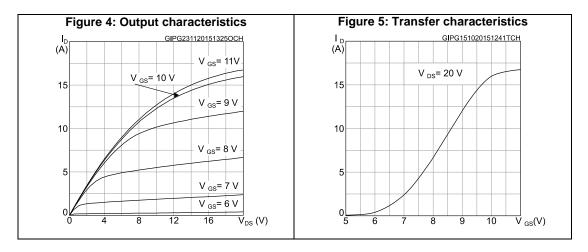
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)GSO</sub>	Gate-source breakdown voltage	$I_{GS}$ = ± 1mA, $I_{D}$ = 0 A	30	-	-	V

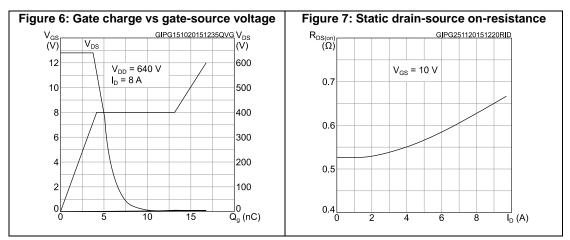
The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.



2.2



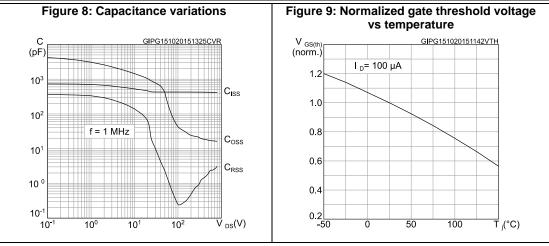


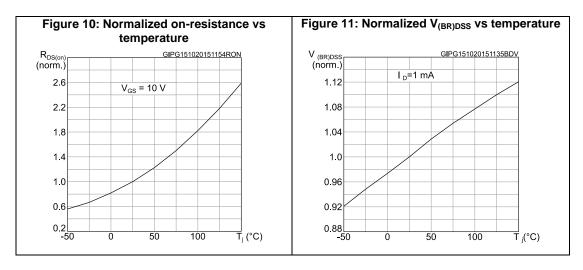


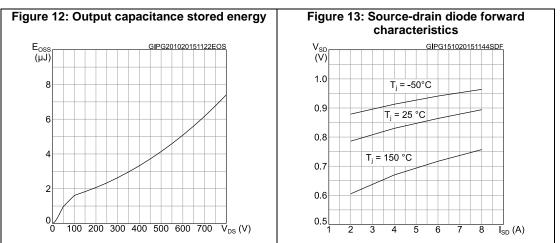


#### STP10LN80K5

#### **Electrical characteristics**



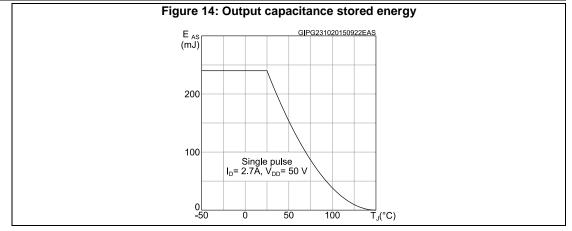






#### **Electrical characteristics**

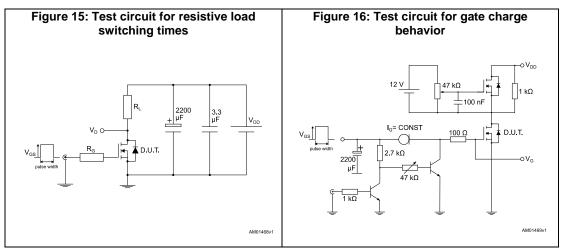
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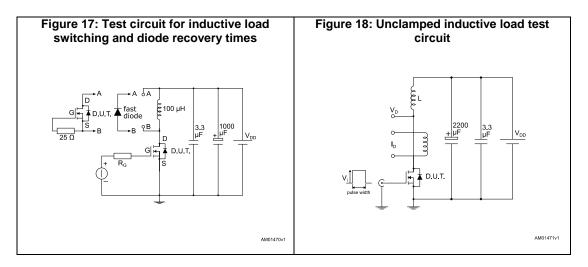


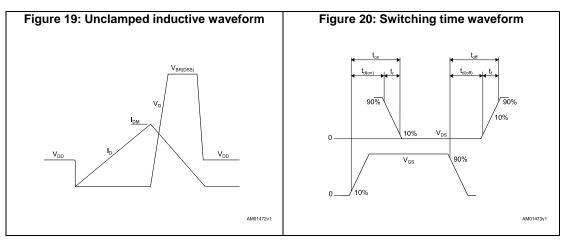
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### **3** Test circuits









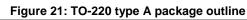
## 4 Package information

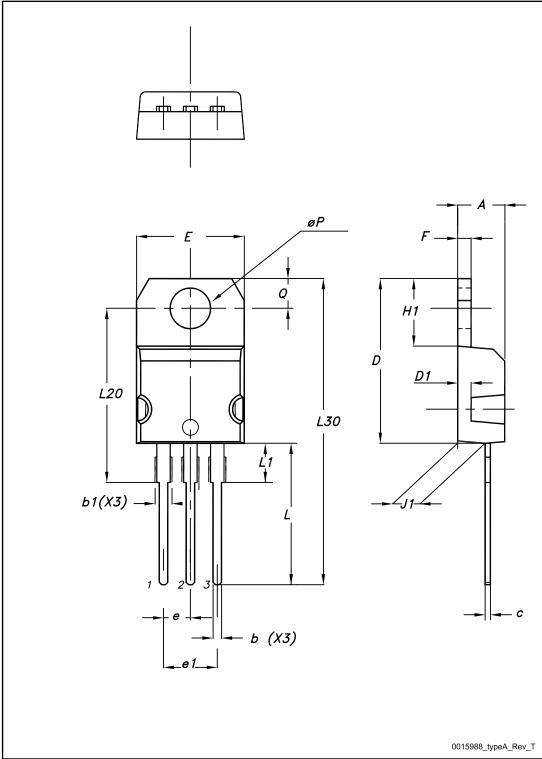
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK<sup>®</sup> is an ST trademark.



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## 4.1 TO-220 type A package information





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#### Package information

#### STP10LN80K5

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	Table 10: TO-220 ty	pe A mechanical data			
Dim		mm			
Dim.	Min.	Тур.	Max.		
A	4.40		4.60		
b	0.61		0.88		
b1	1.14		1.70		
С	0.48		0.70		
D	15.25		15.75		
D1		1.27			
E	10		10.40		
е	2.40		2.70		
e1	4.95		5.15		
F	1.23		1.32		
H1	6.20		6.60		
J1	2.40		2.72		
L	13		14		
L1	3.50		3.93		
L20		16.40			
L30		28.90			
øP	3.75		3.85		
Q	2.65		2.95		



## 5 Revision history

Date	Revision	Changes
10-Jun-2015	1	First release.
14-Dec-2015	2	Datasheet promoted from preliminary data to production data Modified: Table 2: "Absolute maximum ratings", Table 3: "Thermal data", Table 4: "Avalanche characteristics", Table 5: "On/off-state", Table 6: "Dynamic", Figure 2: "Safe operating area", Figure 3: "Thermal impedance", Figure 4: "Output characteristics" and Figure 7: "Static drain-source on-resistance" Minor text changes



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